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(71) Applicant: **ISMECA SEMICONDUCTOR HOLDING SA** [CH/CH]; Rue de l'Helvétie 283, 2300 La Chaux-de-Fonds (CH).

(72) Inventors: **DE JESUS MENDES NUNES, Marco Manuel**; Résidence Helvétie 85, 2300 La Chaux-de-Fonds (CH). **PALMISANO, Giovanni**; Les Allées 35, 2300 La Chaux-de-Fonds (CH). **TAILLARD, Rémi Eric Patrice**; 2, rue Newton, 25130 Villers-le-Lac (FR). **EME, Thierry**;

25, rue du Neuf Clos, Le Chauffaud, 25130 Villers-le-Lac (FR).

(74) Agent: **P&TS SA**; Av. J.J. Rousseau 4, 2001 Neuchâtel (CH).

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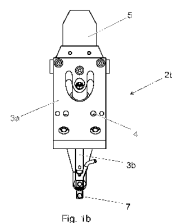


Fig. 1b

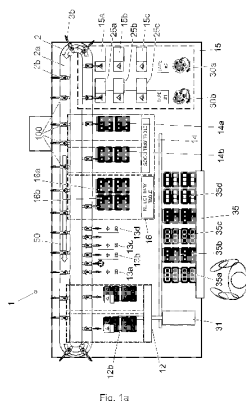


Fig. 1a

(57) Abstract: According to the present invention there is provided a component handling assembly which comprises, a transport system which comprises a track, and a plurality of shuttles, wherein each of said shuttles can be driven individually and independently of one another along the track; and wherein each of said shuttles comprise a pick-up-head which can hold a component; a plurality of stations located proximate to the track, said plurality of stations comprising, a picking station at which the pickup head on a shuttle can pick components from a tray located in said picking station; at least one vision inspection station, which comprises one or more cameras, at which a component which has been picked from the picking station and transported to the vision inspection station can be inspected; and at least one of, a placing station at which the pickup head on a shuttle can place a component onto a tray, and/or, a tape station at which the pickup head on a shuttle can place a component into a pocket of a tape.

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